Smart Sensor Systems for High Temperature Intelligent Engine Applications

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• INTRODUCTION

- INTELLIGENT SYSTEMS FOR HARSH ENVIRONMENTS
- HIGH TEMPERATURE SENSORS FOR CERAMIC MATERIALS
- SIC SENSORS FOR EMISSIONS MONITORING (CERAMIC SENSOR)
- HIGH TEMPERATURE WIRELESS (CERAMIC SEMICONDUCTOR)
- NANOTECHNOLOGY (CERAMIC OXIDE NANOSTRUCTURES)
- SUMMARY



HARSH ENVIRONMENT ELECTRONICS AND SENSORS APPLICATIONS

- NEEDS:
 - > OPERATION IN HARSH ENVIRONMENTS
 - > RANGE OF PHYSICAL AND CHEMICAL MEASUREMENTS
- > INCREASE DURABILITY, DECREASE THERMAL
 - SHIELDING, IMPROVE IN-SITU OPERATION

• RESPONSE: UNIQUE RANGE OF HARSH ENVIRONMENT **TECHNOLOGY AND CAPABILITIES**

- > STANDARD 500°C OPERATION BY MULTIPLE SYSTEMS
- > TEMPERATURE, PRESSURE, CHEMICAL SPECIES, AND WIND AVAILABLE
- > HIGH TEMPERATURE ELECTRONICS TO MAKE SMART SYSTEMS

ALL-IN-ONE SHOP FOR HARSH ENVIRONMENT SYSTEM APPLICATIONS

• ENABLE EXPANDED MISSION PARAMETERS/IN-SITU MEASUREMENTS





1998 R&D 100 Award



1991 R&D 100 Award 1995 R.&D 100 Award

Thin Film Physical Sensors for **High Temperature Applications**

Advantages for temperature, strain, heat flux, flow & pressure measurement:

- Negligible mass & minimally intrusive (microns thick)
- · Applicable to a variety of materials including ceramics
- Minimal structural disturbance (minimal machining)
- + Intimate sensor to substrate contact & accurate placement
- High durability compared to exposed wire sensors
- Capable for operation to very high temperatures (>1000°C)

Multifunctional smart sensors being developed



PdCr strain sensor to T=1000°C



sensor to T=1200°C



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Flow sensor made of high temperature materials



Multifunctional Sensor Array





Novel Thin Film Sensor Technology Development

Development of Thin Film Sensors with Ceramic, Laminate and Nanostructured Materials

- Improve techniques for applying high temperature sensors onto complex structures
- Develop thin film sensors to measure temperature, strain, and heat flux for hot section components

Technology Challenge: Survivability in Extremely High Temperature Environments (>1500°C)

- Build off of experience fabricating devices on more conventional components
- Leverage partnerships with University of Rhode Island and NASA GRC Ceramics Branch for ceramic-based materials



Multilayered Ceramic Sensor with Minimal Apparent Strain Sensitivity

Sputtering System for Thin Film Sensor Fabrication

Ceramic TC Sputtering Targets fabricated by the NASA GRC Ceramics Branch



Ceramic Thermocouple fabricated at University of Rhode Island



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NASA Fundamental Aeronautics

- Program's Supersonics Project
 Weight and temperature barriers for all
- supersonic vehicles
 - Space vehicles (launch/reentry) to military and commercial transport
 - Eliminate factors that limit efficiency and performance of supersonic vehicles
 - > Application to hypersonic regimes as well
- Ceramic Matrix Composite (CMC) components
 - Allows high temperature operation at extended supersonic cruise times
 - > Introduces significant weight reduction
 - Successful implementation of these ceramics requires reliable performance data and life prediction models



1700°C (3100°F) SiC/SiC CMC Turbine Vane Coating System

 Multilayered coating system successfully completed total 100, 1 hr cycle laser heat flux 1700°C test (3100°F, 60 min. hot, 3 min. cool)

 In situ measurements as part of the coating system during tests will better characterize the system

> Currently, conditions on surface

- measured optically > Conditions at interfaces currently interpolated based on bulk thermoconductivity values
- <u>Technical Challenge</u>: Embedded sensors cannot use flame-sprayed attachment or coatings without modifying characteristics
 - New technology needed
 - > Ceramic Thin Film Sensors?



Application of Ceramics as Thin Film Sensors

- The limits of noble metal thin film sensors of 1100°C (2000°F) may not be adequate for the increasingly harsh conditions of advanced aircraft and launch technology (>1650°C/3000°F)
- NASA GRC investigating <u>ceramics as thin</u> <u>film sensors</u> for extremely high temperature applications
- Advantages of the <u>stability and robustness</u> of ceramics and the non-intrusiveness of thin films
- Advances have been made in ceramic thin film sensors through collaborations with the University of Rhode Island (URI)
 - Nanocomposite films are being developed by URI that show potential as thermocouples



Ceramic TC Sputtering Targets fabricated by the NASA GRC Ceramics Branch













High Temperature Wireless Development

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OBJECTIVES:

• HIGH TEMPERATURE WIRELESS TELEMETRY, DISTRIBUTED ELECTRONICS OVER A BROAD OPERATING RANGE

TECHNICAL CHALLENGES:

 DEVELOPMENT OF RELIABLE HIGH TEMPERATURE TELEMETRY ELECTRONICS, POWER SOURCES, REMOTE COMMUNICATION ELECTRONICS, AND PACKAGING

GOALS SUPPORTED:

- ENHANCE PERFORMANCE
- SIGNIFICANTLY REDUCE COST

PROVIDE DATA TRANSFER IN HARSH ENVIRONMENTS IMPROVING RELIABILITY AND ENABLING NEW CAPABILITIES



Prototype Oscillator Circuit

Example: Gas Turbine Engine Development Requires Extensive Instrumentation Yielding Extensive Wiring Complexity



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NASA Glenn Silicon Carbide Differential Amplifier World's First Semiconductor IC to Surpass

4000 Hours of Electrical Operation at 500 °C

Demonstrates CRITICAL ability to <u>interconnect transistors</u> and other components (resistors) in a small area on a single SiC chip to form useful integrated circuits that are durable at 500 °C.



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INTERMEDIATE MILESTONE

 BREADBOARD DEMONSTRATION OF POWER SCAVENGING AT 300°C WITH 3V VOLTAGE, PRESSURE SENSOR AT 300°C, AND A WIRELESS CIRCUIT WITH RF COMMUNICATION AT 300°C OVER 1M DISTANCE. (FY09Q4) PREPARE FOR 500°C BY MAKING A SYSTEM WORK AT 300°C. THIS MILESTONE IS A TRIAL AND PROVING GROUND FOR:

- > SYSTEM APPROACHES AND INTEGRATION NEEDED FOR 500° C OPERATION
- > CHARACTERIZATION AND BENCHMARKING OF OPERATIONAL SENSOR SYSTEMS OPERABLE AT 300°C
- > IDENTIFY TECHNOLOGY CONCENTRATION AREAS WHICH WILL BE NEEDED FOR 500°C OPERATION

• OVERALL APPROACH IS TO USE EXISTING TECHNOLOGIES AT 300°C IF VIABLE > DEVELOP WHAT IS NEEDED FOR THE MILESTONE/LEVERAGE THE REST

• MILESTONE BRINGS TOGETHER MULTIPLE FIELDS OF EXPERTISE IN HIGH TEMPERATURE TECHNOLOGY

· NECESSARY COMPONENTS FOR MILESTONE DEMONSTRATION

- > PRESSURE SENSOR (COMMERCIAL SILICON BASED SENSOR)
- > POWER SUPPLY (COMMERCIAL POWER SCAVENGING MODULE)
- > SIC CIRCUITY (COMMERCIAL MESFET CIRCUIT)
- > WIRELESS CIRCUIT
- > SYSTEM INTEGRATION
- > TESTING SYSTEM

WIRELESS CIRCUIT

 PREVIOUS WORK AND CIRCUIT DESIGNS ARE INSUFFICIENT TO MEET THIS MILESTONE/TARGETED SYSTEM DEVELOPMENT NECESSARY

· SIGNIFICANT ADVANCEMENTS MADE

 DEVELOPED AND CHARACTERIZED THIN FILM COMPONENTS (MIM CAPACITORS AND THIN FILM SPIRAL INDUCTORS) TO 400°C

- DEVELOPED AND CHARACTERIZED PLANAR ANTENNAS TO 400°C
- DEVELOPED AND CHARACTERIZED OSCILLATORS OPERATING AT 30, 100, 800, AND 1000 MHZ
 - · OPERATED 800 AND 1000 MHZ OSCILLATORS TO 270°C
 - · OPERATED 30 AND 100 MHZ OSCILLATORS TO 470°C
- DEVELOPED AND CHARACTERIZED TRANSMISSION LINES ON BOTH SAPPHIRE AND ALUMINA SUBSTRATES TO 400°C
- DESIGNED MINIATURE ANTENNAS UTILIZING CAPACITIVE LOADING TECHNIQUES ON FOLDED SLOT ANTENNAS TO REDUCE OVERALL SIZE OF THE
- WIRELESS PRESSURE SENSOR. DEVELOPED THIN FILM PECVD SIC PACKAGING TECHNOLOGY FOR HIGH
- TEMPERATURE ELECTRONICS AND HARSH ENVIRONMENTS

IT SHOULD BE NOTED THAT EACH OF THESE ARE CONSIDERED WORLD FIRSTS. NOTABLE SYSTEM INTEGRATION USING THIN FILM APPROACHES

ACTIVITIES IN RED CONSIDERED PARTICULARLY SIGNIFICANT AND FOUNDATIONAL FOR 500° C OPERATION





SYSTEM INTEGRATION AND TESTING

• DESIGNED HIGH TEMPERATURE PRESSURE VESSEL WHICH ALLOWED WIRELESS SENSOR TO TRANSMIT OVER A 1 METER DISTANCE TO RECEIVING ANTENNA WHILE UNDER VARIOUS PRESSURES AND TEMPERATURE RANGES FROM 25°C TO 300°C.



Circuit installed inside chamber



OBJECTIVE : TO MOVE TOWARD HIGHER DEGREES OF COMPLEXITY ALLOWING WIRELESS TRANSMISSION AND HARSH ENVIRONMENT SMART SENSOR SYSTEMS

Overall Approach:

Smart Systems in High Temperature Environments Milestone: Demonstrate High Temperature Sensing, Wireless Communication, and Power Scavenging for Propulsion Health Management 8/30/2011

Metric:

Demonstrate integrated self powered wireless sensor system at 500°C with data transmission with operational life of at least 1 hr

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SUMMARY

- AEROSPACE APPLICATIONS REQUIRE A RANGE OF SENSING TECHNOLOGIES
- A RANGE OF SENSOR AND SENSOR SYSTEM TECHNOLOGIES BEING DEVELOPED USING MICROFABRICATION AND MICROMACHINING TECHNOLOGY TO FORM SMART SENSOR SYSTEMS AND INTELLIGENT CHEMICAL MICROSYSTEMS
- DRIVE SYSTEM INTELLIGENCE TO THE LOCAL (SENSOR) LEVEL
 DISTRIBUTED SMART SENSOR SYSTEMS
- SENSOR AND SENSOR SYSTEM DEVELOPMENT RELATED TO CERAMICS
 - >HIGH TEMPERATURE SENSORS FOR CERAMIC MATERIALS
 - THE 1700°C EBC-CMC SYSTEMS UNDER DEVELOPMENT REQUIRE INTEGRATED SENSORS TO ALLOW A MORE COMPLETE CHARACTERIZATION
 - HEAT FLUX SENSORS WERE FABRICATED WITH NANOCOMPOSITES
 - BEST RESULTS FROM PRELIMINARY DATA WAS A RESPONSE OF 0.06 \pm 0.02 $\mu V/(W/CM^2)$ WAS MEASURED
 - > SIC SENSORS FOR EMISSIONS MONITORING (CERAMIC SENSOR)
 - HIGH SENSITIVITY GAS SENSORS BASED ON SIC SCHOTTKY DIODES
 - INTERACE CONTROL FUNDAMENTAL TO OPERATION
 - HIGH TEMPERATURE ELECTRONIC NOSE APPROACH BEING TESTED
 - > HIGH TEMPERATURE WIRELESS (CERAMIC SEMICONDUCTOR)
 - WORLD LEADING WORK IN HIGH TEMPERATURE ELECTRONICS
 - INTEGRATION INTO A HIGH TEMPERATURE WIRELESS SYSTEM
 - WIRELESS TRANSMISSION AT 300°C DEMONSTRATED
 - > NANOTECHNOLOGY (CERAMIC OXIDE NANOSTRUCTURES)
 - SIGNIFICANT PROMISE BUT TECHNOLOGY BARRIERS EXIST
 - EMPHASIS ON CREATING OPERATIONAL MICROSENSORS

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